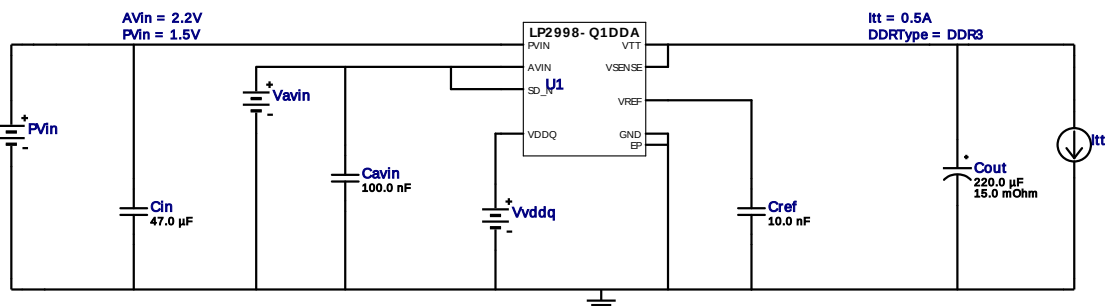




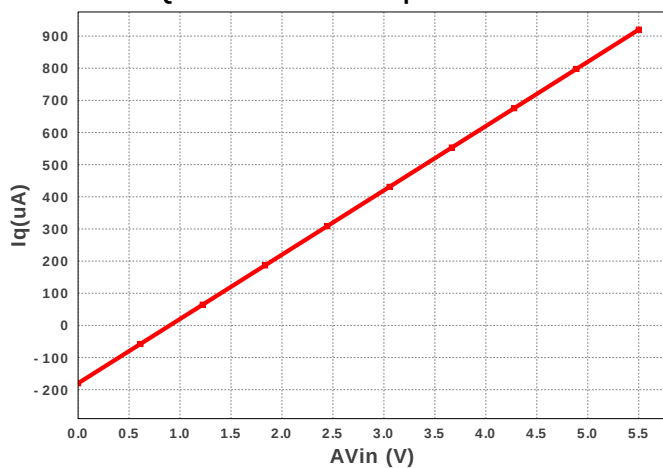
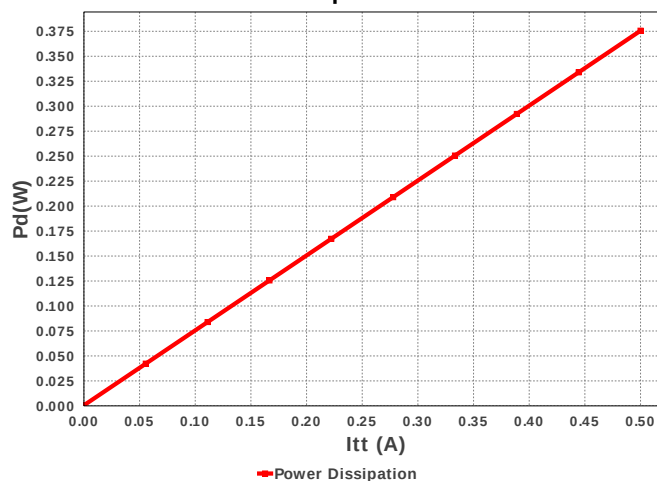
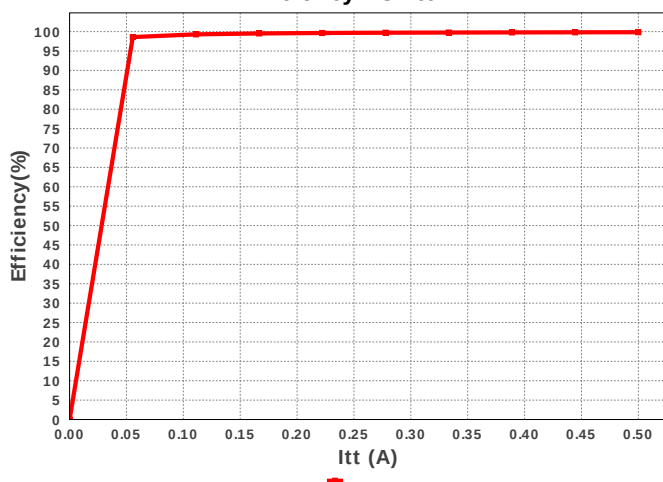
My Comments

No comments

Electrical BOM

#	Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
1.	Cvin	MuRata	GRM155R60J104KA01D Series= X5R	Cap= 100.0 nF VDC= 6.3 V IRMS= 0.0 A	1	\$0.01	0402 3 mm ²
2.	Cin	Taiyo Yuden	JMK212BJ476MG-T Series= X5R	Cap= 47.0 uF VDC= 6.3 V IRMS= 0.0 A	1	\$0.14	0805 7 mm ²
3.	Cout	Panasonic	2R5TPE220MAFB Series= ?	Cap= 220.0 uF ESR= 15.0 mOhm VDC= 2.5 V IRMS= 2.0 A	1	\$0.50	CAPSMT_6_B2S 17 mm ²
4.	Cref	MuRata	GRM155R60J103KA01D Series= X5R	Cap= 10.0 nF VDC= 6.3 V IRMS= 0.0 A	1	\$0.01	0402 3 mm ²
5.	U1	Texas Instruments	LP2998QMRE/NOPB	Switcher	1	\$0.81	DDA0008A 57 mm ²

Quiescent Current Iq Vs. AVin

Power Dissipation Vs. I_{tt}Efficiency Vs. I_{tt}

Operating Values

#	Name	Value	Category	Description
1.	BOM Count	5	General	Total Design BOM count
2.	FootPrint	87.0 mm ²	General	Total Foot Print Area of BOM components
3.	Total BOM	\$1.47	General	Total BOM Cost
4.	AVin_OP	2.2 V	Op_Point	Pvin operating point
5.	I _{tt} _OP	500.0 mA	Op_Point	I _{tt} Operating Point
6.	PVin_OP	1.5 V	Op_Point	Pvin operating point
7.	T _a _OP	35.0 degC	Op_Point	Operating Ambient Temperature
8.	V _{ddq} _OP	1.5 V	Op_Point	V _{ddq} operating point
9.	V _{tt} _OP	750.0 mV	Op_Point	V _{tt} operating point
10.	Efficiency	99.842 %	Op_point	Steady state efficiency
11.	IC T _j	51.151 degC	Op_point	IC junction temperature
12.	ICThetaJA	43.0 degC/W	Op_point	IC junction-to-ambient thermal resistance
13.	Total Pd	375.594 mW	Power	Total Power Dissipation

Design Inputs

#	Name	Value	Description
1.	AVin	2.2 A	AVin
2.	DDRTYPE	DDR3	DDRTYPE
3.	I _{tt}	500.0 mA	I _{tt}
4.	PVin	1.5 A	PVin
5.	application	DDRPower	application
6.	base_pn	LP2998-Q1	Base Product Number
7.	T _a	35.0 A	Ambient temperature

Design Assistance

1. **LP2998-Q1** Product Folder : <http://www.ti.com/product/lp2998> : contains the data sheet and other resources.

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